

Electronic Patent Application Fee Transmittal

Application Number:	10801475			
Filing Date:	16-Mar-2004			
Title of Invention:	SYSTEM FOR HEAT DISSIPATION IN SEMICONDUCTOR DEVICES			
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Filer:	David M. Odell/Lydia Epps-Hilliard			
Attorney Docket Number:	24061.193 (TSMC2003.1410)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
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Total in USD (\$)				1740